ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pan-	C, Bannock	burn, Illinois. A	ll rights reserved utions.	under both	This docume level parts, t	ent is a decla	ration of	the substance passes all lo	ces with wer lev	in the manufactur el materials for wl	er listed it hich the m	em. Note anufactu	e: if the item arer has engi	i is an assen neering resj	bly with low ponsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
upplier Information															
Company name* Company unique ID						Unique ID Authority					Response Date*				
nsemi						2024-05-09									
Contact Name Title - Contact						Phone - Contact*					Email - Contact*				
Product-Env-Stewards Product Enviro Compliance			ro Compliance			NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Representative					Phone - Representative*					Email - Representative*					
Product-Env-Stewards Pr			roduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Iten	n Number	Mfr Item Name				ate Ve	ersion	Manu	Manufacturing Site		Weight*	UO	М	Unit Type
	AR0130 0-DPBR	CSSC00SPCA 1.2 MP 1/3 CIS				2024-05-09)		TA1	TA1		264.22	mg		Each
Ianufacturing Proccess Informat	ion														
Terminal Plating / Grid Array Mat	erial	Ferminal Base A	erminal Base Alloy J-STD-020 M		L Rating	Peak P	A Process Body Temperature Max Time at Pe		Iax Time at Peak	Temperature Number of Reflow Cy		low Cycles			
Precious metal (e.g. Ag,Au, NiPo Sn)	Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy 4 Sn)		4		260 C		C	3	30 seco		ds 3				
omments									I			•			
or more information regarding material c	omposition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead b), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl athalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the complicate of its products with European Union member states) by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.												
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	57.0	mg		Misc.	proprietary data		0.2166	mg
			Supplier	Silicon (Si)	7440-21-3		56.2191	mg
			Supplier	Aluminum (Al)	7429-90-5		0.5643	mg
Die Attach	2.5	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.9375	mg
			Supplier	Ethylene Glycol	107-21-1		0.025	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.075	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.525	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.9375	mg
Imaging Lens	60.5	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		3.025	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		3.025	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		3.025	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		3.025	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.3025	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		3.025	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		3.025	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		42.0475	mg
Lid Attach	2.6	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.8216	mg
			Supplier	Filler (SiO2)	68909-20-6		0.1352	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.8216	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.8216	mg
Mold Compound-Black	54.0	mg		Phenolic Resin	proprietary data		8.1	mg
			Supplier	Oxirane	39817-09-9		8.1	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.62	mg
			Supplier	Carbon Black (C)	1333-86-4		0.54	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.56	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.08	mg
ubstrate and Solder Mask	87.4	mg	Supplier	Acetophenone	98-86-2		1.713	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		19.3941	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		1.1449	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.1537	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2884	mg

			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2884	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.4261	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	8.74	mg
			Supplier	Copper (Cu)	7440-50-8	42.389	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	8.8624	mg
Wire Bond - Au	0.22	mg	Supplier	Gold (Au)	7440-57-5	0.22	mg